

**In the Specification:**

After the title, please insert the sentence: --This is a continuation of application

91 Serial No. 09/239,617 filed January 29, 1999.--

**In the Claims:**

Please cancel claims 1-90.

Please add the following new claims:

92 --91. An integrated module comprising:

a single interconnect substrate;

a first active circuit chip wire bonded to said single interconnect substrate;

a first discrete component surface mounted on said single interconnect substrate;

and

a second discrete component embedded in said single interconnect substrate.--

--92. The integrated module of claim 91 wherein said first discrete component is surface mounted using a high-temperature solder.--

--93. The integrated module of claim 91 further comprising a solder mask area on said single interconnect substrate.--

--95. The integrated module of claim 91 wherein said first discrete component is selected from the group consisting of an inductor, a transformer, a capacitor, and a resistor.--

--96. The integrated module of claim 91 wherein said second discrete component is selected from the group consisting of an inductor, a transformer, a capacitor, and a resistor.--

--97. The integrated module of claim 91 wherein said single interconnect substrate comprises a plurality of metal layers and a plurality of dielectric layers.--

--98. The integrated module of claim 97 wherein at least one of said plurality of metal layers defines a printed component.--

--99. The integrated module of claim 98 wherein said printed component is selected from the group consisting of an inductor, a resistor, a capacitor, and a transformer.--

--100. The integrated module of claim 97 wherein at least one of said plurality of metal layers defines a ground plane.--

--101. The integrated module of claim 91 wherein said first active circuit chip comprises an RF section.--

--102. The integrated module of claim 91 wherein said first active circuit chip comprises an IF section.--

--103. The integrated module of claim 91 further comprising a second active circuit chip.--

--104. The integrated module of claim 103 wherein said first and second active circuit chips respectively comprise first and second RF sections.--

--105. The integrated module of claim 103 wherein said first active circuit chip comprises an RF section and wherein said second active circuit chip comprises an IF section.--

--106. The integrated module of claim 103 wherein said first active circuit chip comprises a CMOS chip and wherein said second active circuit chip comprises a GaAs chip.--

--107. The integrated module of claim 97 wherein at least one of said plurality of metal layers defines said first discrete component.--

--108. The integrated module of claim 107 wherein said first discrete component is selected from the group consisting of an inductor, a resistor, a capacitor, and a transformer.--

--109. The integrated module of claim 97 wherein at least one of said plurality of metal layers defines said second discrete component.--

--110. The integrated module of claim 109 wherein said second discrete component is selected from the group consisting of an inductor, a resistor, a capacitor, and a transformer.--

--111. An integrated module comprising:  
a single interconnect substrate including a plurality of metal layers and a plurality of dielectric layers;

first and second active circuit chips on a top surface of said single interconnect substrate;

a conductive ring formed on said single interconnect substrate, said conductive ring enclosing said first and second active circuit chips;

a conductive strip formed on said single interconnect substrate, said conductive strip situated between said first and second active circuit chips;

a metal lid covering said first and second active circuit chips, said metal lid contacting said conductive ring and said conductive strip, wherein said metal lid, said

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--113. The integrated module of claim 112 wherein said first ground plane is defined by at least one of said plurality of metal layers below said first active circuit chip.--

--115. The integrated module of claim 114 wherein said second ground plane is defined by at least one of said plurality of metal layers below said second active circuit chip.--

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--117. The integrated module of claim 112 wherein said conductive ring is coupled to said first ground plane through a plurality of peripheral vias.--

--118. The integrated module of claim 114 wherein said conductive ring is coupled to said second ground plane through a plurality of peripheral vias.--

--119. The integrated module of claim 111 wherein said conductive strip is coupled to ground through a plurality of peripheral vias.--

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FOOTNOTES